

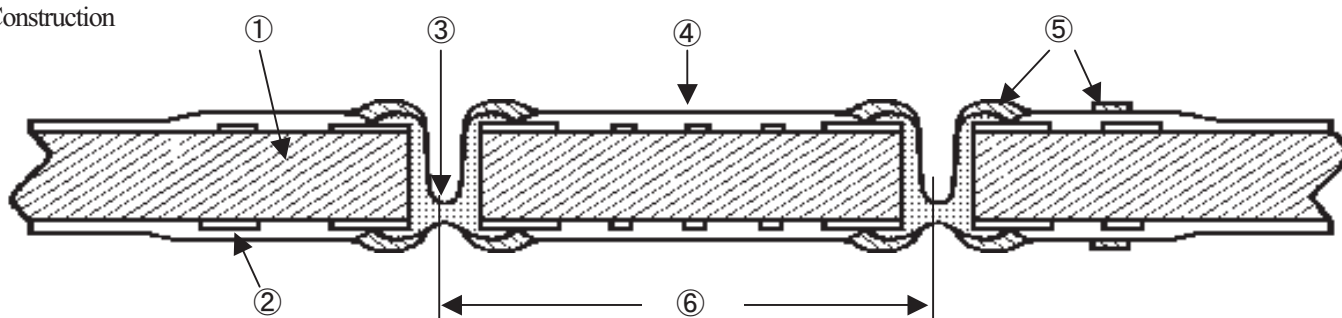


Double Sided (Silver / Copper) Polymer Through Hole Board

■ Features

- Significant cost reduction is possible by replacing copper plating through-hole PWB with polymer through-hole PWB.
- High density circuit design is widely available.
- Double sided surface mount PWB is available by using polymer through-hole PWB.
- Highly reliable PWB is realized by using polymer through-holes on paper phenolic board.

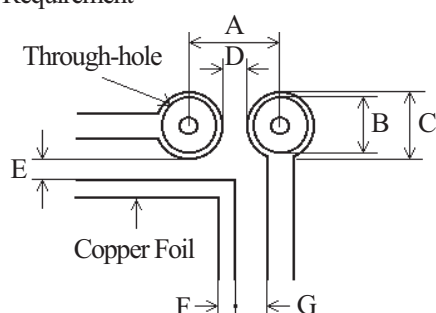
■ Construction



No.	Name	No.	Name
①	Base	④	Solder Resist
②	Copper Foil	⑤	Covercoat & Marking
③	Through-hole	⑥	Through-hole Pitch

(mm)

■ Design Requirement



Through-hole Pitch:A	C	D	E	F	G
1.00	0.80	0.20	0.25	0.20	0.20
1.25	1.00	0.25	0.25	0.20	0.20
1.50	1.20	0.30	0.30	0.20	0.20
1.75	1.40	0.35	0.40	0.20	0.20
2.00	1.50	0.50	0.50	0.20	0.20
2.50	2.00	0.50	0.50	0.20	0.20

■ Specification

Item	Specification		Condition
	AgTh	CuTh	
Material of Base	FR-1, CEM-3		
Through-hole	Conductive Resin		Copper paste through-hole pitch: Min. 1.25mm
	Silver Paste	Copper Paste	
Ambient Temperature	-30 ~ +100°C		
Through-hole Resistance	100mΩ /hole	100mΩ /hole	
Rated Current	300mA/hole	300mA/hole	Less than 1.25mm pitch:250mA/hole
Max. Operation Voltage	50V *(20V)	100V	Different electric potential Voltage (*Applied less than 1.25mm pitch)
Load Life	200mΩ /hole	200mΩ /hole	70°C 1000Hr
Humidity Load Life	200mΩ /hole	200mΩ /hole	40°C 90~95%RH 1000Hr
High Temperature	200mΩ /hole	200mΩ /hole	100°C 1000Hr
Humidity	200mΩ /hole	200mΩ /hole	40°C 90~95%RH 1000Hr
Solder Dipping	200mΩ /hole	200mΩ /hole	260°C 5sec.
Reflow	200mΩ /hole	200mΩ /hole	240°C 3sec.
Migration	200mΩ /hole	200mΩ /hole	40°C 90~95%RH 1000Hr
Oil Dipping	200mΩ /hole	200mΩ /hole	260°C 10sec 100 Cycle
Heat Cycle	200mΩ /hole	200mΩ /hole	-40°C⇄100°C 30min. 100 cycle



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Characteristic (Reference Data)

Ag Th : Ag Paste (1.5mm pitch, FR-1, t=1.6mm)

Cu Th : Copper Paste (1.5mm pitch, FR-1, t=1.6mm)

